

SAC57D54HCVMO :Part Detail

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General Information

Part Number	SAC57D54HCVMO
Description	ARM 32-bit MCU, Triple core, 4MB Flash, 1.3MB gRAM, 1MB sysRAM, -40/+105degC, 516 MAPBGA
Product Line	G9V5756H
PTI	JBGE
Material Type	Tested Packaged Device
Life Cycle Description (code)	PRODUCT RAPID GROWTH
Status	Active
Application/Qualification Tier	AUTO; >=10 YEARS APPLICATION LIFE

Package Information

Package Type and Termination Count	MAPBGA 516
Package Description and Mechanical Drawing	MAPBGA 516 27SQ*2.0 P1.0
Device Weight(g)	2.91110
Package Length (nominal)(mm)	27.000
Package Width (nominal)(mm)	27.000
Package Thickness (nominal)(mm)	1.830
Tape & Reel	No

Environmental and Compliance Information

Pb-Free	
RoHS Compliant	
Halogen Free	Yes
Material Composition Declaration (MCD)	Download MCD Report  Download MCD Report 
RoHS Certificate of Analysis (CoA)	Contact Us
2nd Level Interconnect	e2
Moisture Sensitivity Level (MSL)	3
Floor Life	168 HOURS
Peak Package Body Temperature (PBT)(°C)	260

Maximum Time at Peak Temperature (s)	40
Number of Reflow Cycles	3
REACH SVHC	NXP REACH Statement
UL94 (plastics flammability test)	V0;Burning stops within 10 seconds on a vertical specimen;no drips allowed

Manufacturing Information

Micron Size(μm)	.05
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Ordering Information

Minimum Package Quantity (MPQ)	200
MPQ Container	BRICK
Exempt from Minimum Delivery Value	Yes
Preferred Order Quantity (POQ)	400
POQ Container	BOX
Leadtime (weeks)	20
Export Control Classification Number (US)	5A002A
Harmonized Tariff (US) Disclaimer	8542.31.0000
CCATS Document	-
ENC Status	-
Other Trade Compliance Documents	-
Budgetary Price excluding tax(US\$) Change Currency	-

Order

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 Sample

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Operating Characteristics

Additional Features	MLB50 10/100
CAN	3
Core Type	ARM Cortex-M4 ARM Cortex-M0+ IOP ARM Cortex-A5
Core: Number of cores (Spec)	3
eDMA	2x 16ch
External Memory Supported	32-Bit DDR2 DRAM (320mhz) 16-Bit SDR DRAM (160mhz) 2x Dual DDR QuadSPI
I2C	2

Internal Flash (KB)	4000
Internal RAM (KB)	1300
L1 Cache	32/32 on A5
LinFlex D	3
Memory / Peripheral Protection	Yes
Operating Frequency (Max) (MHz)	320
Sample Exception Availability	Y
SPI	5
Timer/PWM	8ch PIT 3x SWT ARTC 4x 8ch Flextimer
Video/Display features	2x 2D-ACE HUD Warping Engine Video Input Unit Segment LCD OpenVG 1.1

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